

### SEMITRANS® 10

### **IGBT R8 Modules**

#### SKM1400GB17R8

#### Features\*

- · Symmetrical current sharing
- Low-inductive module design
- High mechanical robustness
- UL recognized, file no. E63532

#### **Typical Applications**

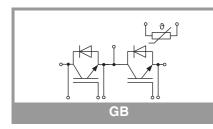
- Motor Drives
- UPS Systems
- Solar Inverters

#### Remarks

Recommended  $T_{jop} = -40 \dots + 150^{\circ}C$ 

**Absolute Maximum Ratings** Symbol Conditions Values Unit IGBT T<sub>i</sub> = 25 °C ۷ 1700  $V_{CES}$ T<sub>c</sub> = 25 °C 2337 А lc T<sub>i</sub> = 175 °C T<sub>c</sub> = 100 °C 1527 А I<sub>Cnom</sub> 1400 А 2800 Α **I**CRM V<sub>GES</sub> -20 ... 20 V V<sub>CC</sub> = 1200 V  $V_{GE} \le 15 \text{ V}$ T<sub>i</sub> = 150 °C 10 μs t<sub>psc</sub>  $V_{CES} \le 1700 \text{ V}$ °C T<sub>i</sub> -40 ... 175 Inverse diode T<sub>j</sub> = 25 °C 1700 V V<sub>RRM</sub> T<sub>c</sub> = 25 °C 1874 А  $\mathsf{I}_\mathsf{F}$ T<sub>j</sub> = 175 °C T<sub>c</sub> = 100 °C 1168 А 2800 А I<sub>FRM</sub>  $t_p$  = 10 ms, sin 180°,  $T_j$  = 25 °C 9024 А  $I_{FSM}$ °C Tj -40 ... 175 Module T<sub>stg</sub> -40 ... 150 °C AC sinus 50 Hz, t = 1 min 4000 ٧  $V_{\text{isol}}$ 

Characte	eristics					
Symbol	Conditions		min.	typ.	max.	Unit
IGBT						
V <sub>CE(sat)</sub>	I <sub>C</sub> = 1400 A	T <sub>j</sub> = 25 °C		1.63	1.95	V
V <sub>GE</sub> = 15 V chiplevel		T <sub>j</sub> = 150 °C		1.96	2.27	V
V <sub>CE0</sub>	chiplevel	T <sub>j</sub> = 25 °C		1.06	1.12	V
		T <sub>j</sub> = 150 °C		0.95	1.05	V
r <sub>CE</sub>	V <sub>GE</sub> = 15 V chiplevel	T <sub>j</sub> = 25 °C		0.41	0.59	mΩ
		T <sub>j</sub> = 150 °C		0.72	0.87	mΩ
V <sub>GE(th)</sub>	V <sub>CE</sub> = 10 V, I <sub>C</sub> = 52.8 mA		5	5.8	6.5	V
I <sub>CES</sub>	$V_{GE} = 0 \text{ V},  V_{CE} = 1700 \text{ V},  T_{j} = 25 ^{\circ}\text{C}$				6.0	mA
Cies	V <sub>CE</sub> = 25 V V <sub>GE</sub> = 0 V	f = 1 MHz		139.2		nF
C <sub>oes</sub>		f = 1 MHz		4.80		nF
C <sub>res</sub>		f = 1 MHz		0.43		nF
Q <sub>G</sub>	V <sub>GE</sub> = -15V/+15V			8640		nC
R <sub>Gint</sub>	T <sub>j</sub> = 25 °C			1.3		Ω
t <sub>d(on)</sub>	$V_{CC} = 900 V$ $I_{C} = 1400 A$ $V_{GE} = +15/-15 V$ $R_{G on} = 0.67 \Omega$ $R_{G off} = 0.5 \Omega$	T <sub>j</sub> = 150 °C		558		ns
t <sub>r</sub>		T <sub>j</sub> = 150 °C		140		ns
Eon		T <sub>j</sub> = 150 °C		866		mJ
t <sub>d(off)</sub>		T <sub>j</sub> = 150 °C		666		ns
t <sub>f</sub>	di/dt <sub>on</sub> = 7.5 kA/µs	T <sub>j</sub> = 150 °C		200		ns
E <sub>off</sub>	di/dt <sub>off</sub> = 6.1 kA/ $\mu$ s dv/dt = 4200 V/ $\mu$ s L <sub>s</sub> = 25 nH	T <sub>j</sub> = 150 °C		495		mJ
R <sub>th(j-c)</sub>	per IGBT				0.02	K/W
R <sub>th(c-s)</sub>	per IGBT (λ <sub>grease</sub> =0.81 W/(m*K))			0.01		K/W





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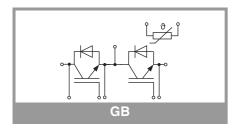
#### **Typical Applications**

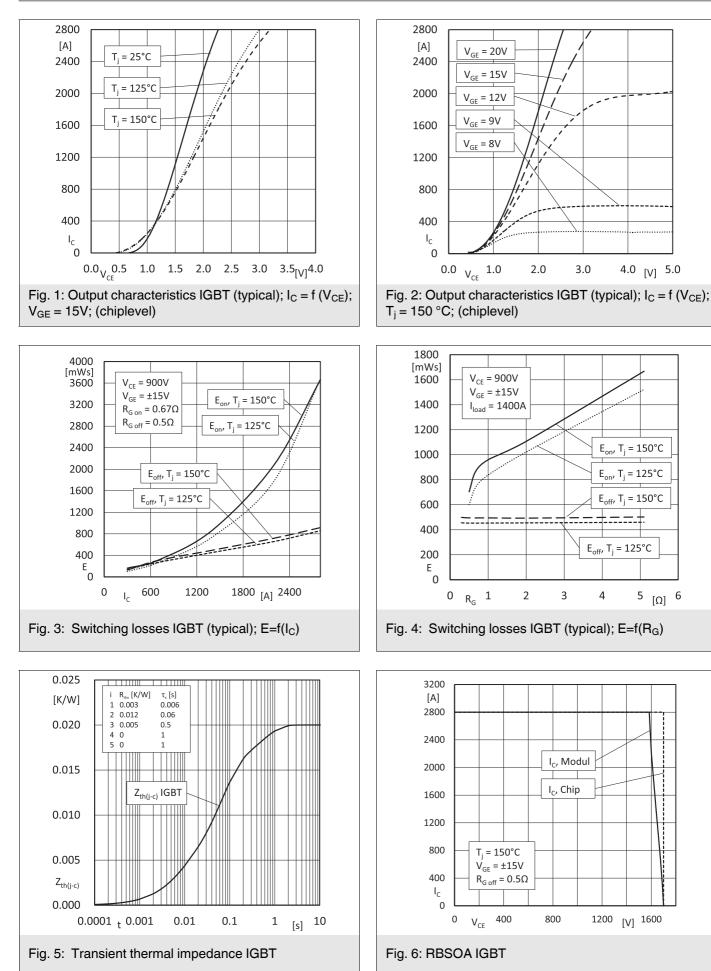
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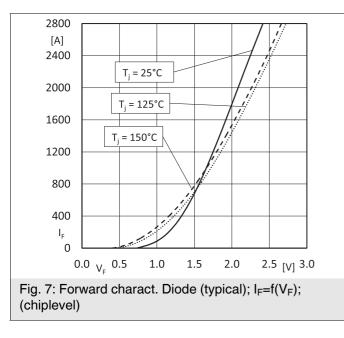
Symbol	Conditions	min.	typ.	max.	Unit	
Inverse d						
$V_F = V_{EC}$	1	T <sub>i</sub> = 25 °C		1.84	2.19	V
1 20		T <sub>j</sub> = 150 °C		1.89	2.25	V
V <sub>F0</sub>	chiplevel	T <sub>j</sub> = 25 °C		1.32	1.56	V
		T <sub>j</sub> = 150 °C		1.08	1.22	V
r <sub>F</sub>	chiplevel	T <sub>j</sub> = 25 °C		0.37	0.45	mΩ
		T <sub>j</sub> = 150 °C		0.58	0.74	mΩ
I <sub>RRM</sub>	$I_{F} = 1400 \text{ A} \\ di/dt_{off} = 7.8 \text{ kA/}\mu\text{s} \\ V_{GE} = -15 \text{ V} \\ V_{CC} = 900 \text{ V} $	T <sub>j</sub> = 150 °C		925		Α
Q <sub>rr</sub>		T <sub>j</sub> = 150 °C		495		μC
E <sub>rr</sub>		T <sub>j</sub> = 150 °C		253		mJ
R <sub>th(j-c)</sub>	per diode				0.032	K/W
R <sub>th(c-s)</sub>	per diode ( $\lambda_{grease}$ =0.81 W/(m*K))			0.013		K/W
Module		÷				
L <sub>CE</sub>				10		nH
R <sub>CC'+EE'</sub>	measured per switch, $T_C = 25 \ ^{\circ}C$		0.2			mΩ
R <sub>th(c-s)1</sub>	calculated without thermal coupling $(\lambda_{grease}=0.81 \text{ W}/(\text{m}^{\star}\text{K}))$		0.0028			K/W
R <sub>th(c-s)2</sub>	including thermal coupling, $T_s$ underneath module ( $\lambda_{grease}$ =0.81 W/(m*K))			0.005		K/W
Ms	to heat sink M5		4		6	Nm
Mt		to terminals M8	8		10	Nm
		to terminals M4	1.8		2.1	Nm
w					1250	g
Temperat	ture Sensor					
R <sub>100</sub>	T <sub>c</sub> =100°C (R <sub>25</sub> =5 kΩ)			$493 \pm 5\%$		Ω
B <sub>100/125</sub>	$R_{(T)}=R_{100}exp[B_{100/125}(1/T-1/T_{100})]; T[K];$			3550 ±2%		к

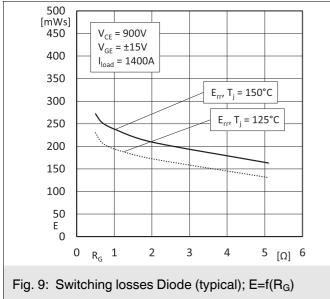


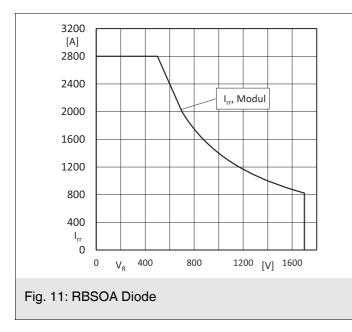


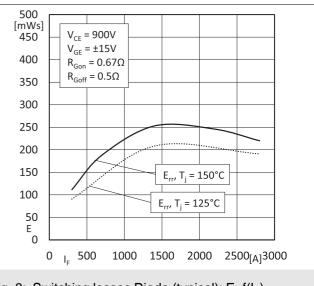
4.0 <sub>[V]</sub> 5.0

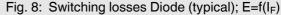
5 <sub>[Ω]</sub> 6

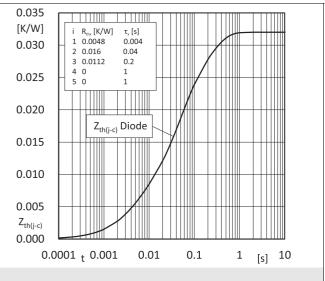


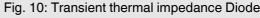


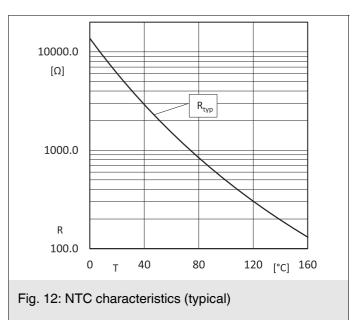


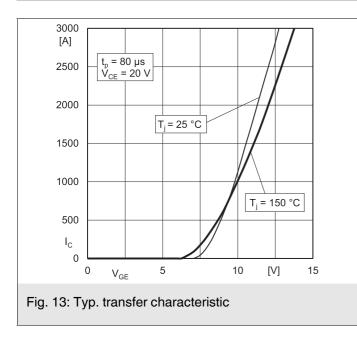


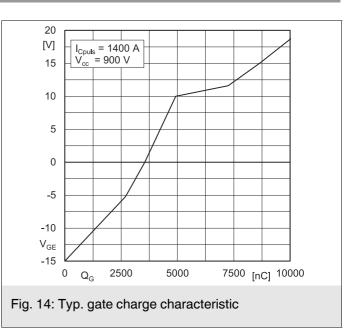


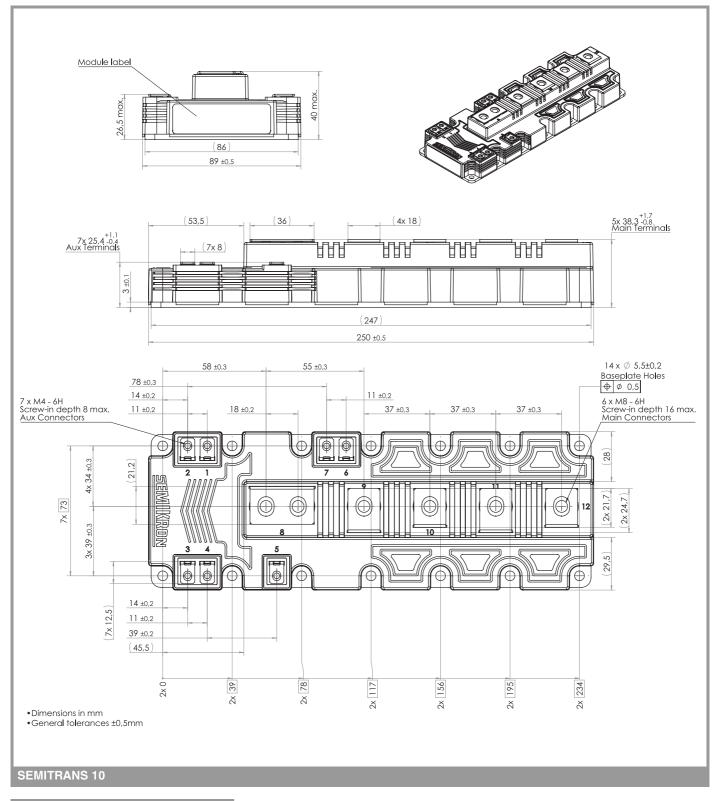


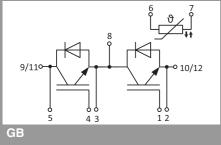












This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, chapter IX.

#### **\*IMPORTANT INFORMATION AND WARNINGS**

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